



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IST011N06NM5	<b>Issued</b>	17. May 2021
<b>MA#</b>	MA005406988		
<b>Package</b>	PG-HSOF-5-4	<b>Weight*</b>	370.49 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.942	1.06	1.06	10639	10639
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.07	13.08	130686	130856
wire	noble metal	gold	7440-57-5	0.037	0.01	0.01	100	100
encapsulation	inorganic material	zinc oxide	1314-13-2	1.396	0.38		3769	
	miscellaneous	miscellaneous	-	5.585	1.51		15075	
	plastics	epoxy resin	-	20.944	5.65		56531	
	inorganic material	silicon dioxide	60676-86-0	111.702	30.15	37.69	301498	376873
lead finish	non noble metal	tin	7440-31-5	3.673	0.99	0.99	9914	9914
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.073	0.02		196	
	noble metal	silver	7440-22-4	0.091	0.02		245	
	non noble metal	lead	7439-92-1	3.467	0.94	0.98	9357	9798
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		76	
	non noble metal	copper	7440-50-8	28.224	7.62	7.63	76180	76279
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		385	
	non noble metal	copper	7440-50-8	142.638	38.51	38.56	384999	385500
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com